PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE: NEW ASSIGNMENT

NATURE OF CONVEYANCE: ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
GU-HUAN LI	03/07/2014
HSU-SHUN CHEN	03/07/2014
CHUNG-CHIEH CHEN	03/07/2014
CHENG-HSIUNG KUO	03/07/2014

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	NO. 8, LI-HSIN RD. VI, HSINCHU SCIENCE PARK
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300

PROPERTY NUMBERS Total: 1

Property Type	Number	
Application Number:	14220663	

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NAME OF SUBMITTER:	RANDY A. NORANBROCK
SIGNATURE:	/Randy A. Noranbrock/
DATE SIGNED:	03/20/2014

Total Attachments: 1

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PATENT REEL: 032487 FRAME: 0480

EPAS ID: PAT2777781

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Docket No. T5057-996 TSMC2013-1730

ASSIGNMENT

In consideration of the premises and othe	r good and valuable	consideration in har	nd paid, the receip	t and sufficiency of
which is hereby acknowledged, the undersigned,			• •	•

Gu-Huan LI

3) Chung-Chieh CHEN

Hsu-Shun CHEN

4) Cheng-Hsiung KUO

who has made a certain new and useful invention, hereby sells, assigns and transfers unto TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD., having a place of business at No. 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300, Taiwan R.O.C.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

SOURCE LINE VOLTAGE REGULATION SCHEME FOR LEAKAGE REDUCTION

(a)	for which an application for United States Letters Patent was filed on 2014-03-20 , United States Patent Application No. 14/220.663 ; or	and	identified	b
(b)	for which an application for United States Letters Patent was executed on,			

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

1) Gu-Huan Li Name: Gu-Huan LI

2) Kzu-Ghin Chen Name: Hsu-Shun CHEN

3) Chung - Weh Wer Name: Chung-Chieh CHEN

4) Cheng - Hsing Kus Name: Cheng Hsiung KUO

PATENT REEL: 032487 FRAME: 0481

RECORDED: 03/20/2014